Irish Standard
I.S. EN 60749-15:2010

Semiconductor devices - Mechanical and climatic test methods -- Part 15: Resistance to soldering temperature for through-hole mounted devices (IEC 60749-15:2010 (EQV))

I.S. EN 60749-15:2010

Incorporating amendments/corrigenda issued since publication:
EN 60749-15:2010/AC:2011

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I.S. xxx: Irish Standard – national specification based on the consensus of an expert panel and subject to public consultation.

S.R. xxx: Standard Recommendation - recommendation based on the consensus of an expert panel and subject to public consultation.

SWiFT xxx: A rapidly developed recommendatory document based on the consensus of the participants of an NSAI workshop.

This document replaces:	*This document is based on:*	*Published:*
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Corrigendum to EN 60749-15:2010

English version

Foreword

Delete the following sentence: "Annex ZA has been added by CENELEC."

February 2011

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I.S. EN 60749-15:2010

EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN 60749-15

December 2010

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Supersedes EN 60749-15:2003

English version

Semiconductor devices - Mechanical and climatic test methods - Part 15: Resistance to soldering temperature for through-hole mounted devices

(IEC 60749-15:2010)

Dispositifs à semiconducteurs - Méthodes d'essai mécaniques et climatiques - Partie 15: Résistance à la température de soudage pour dispositifs par trous traversants (CEI 60749-15:2010)

Halbleiterbauelemente - Mechanische und klimatische Prüfverfahren - Teil 15: Beständigkeit gegen Löttemperatur bei Bauelementen zur Durchsteckmontage (IEC 60749-15:2010)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Management Centre: Avenue Marnix 17, B - 1000 Brussels

Ref. No. EN 60749-15:2010 E

Foreword

The text of document 47/2067/FDIS, future edition 2 of IEC 60749-15, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60749-15 on 2010-12-01.

This European Standard supersedes EN 60749-15:2003.

The significant changes with respect from EN 60749-15:2003 include:

– editorial change in the scope,

– addition of lead-free solder chemical composition specification.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN and CENELEC shall not be held responsible for identifying any or all such patent rights.

The following dates were fixed:

– latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2011-09-01
– latest date by which the national standards conflicting with the EN have to be withdrawn	(dow)	2013-12-01

Annex ZA has been added by CENELEC.

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Endorsement notice

The text of the International Standard IEC 60749-15:2010 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following note has to be added for the standard indicated:

IEC 60068-2-20 NOTE Harmonized as EN 60068-2-20.

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 15: Resistance to soldering temperature for through-hole mounted devices

FOREWORD

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International Standard IEC 60749-15 has been prepared by IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2003 and constitutes a technical revision. The significant changes with respect from the previous edition include:

– editorial change in the scope,
– addition of lead-free solder chemical composition specification.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/2067/FDIS	47/2078/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60749 series, under the general title *Semiconductor devices - Mechanical and climatic test methods*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.